

# Michael G Pecht

## List of Publications by Year in Descending Order

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The third column is the impact factor (IF) of the journal, and the fourth column is the number of citations of the article.

825  
papers

19,776  
citations

66  
h-index

115  
g-index

962  
ext. papers

25,339  
ext. citations

3.6  
avg, IF

7.59  
L-index

#	Paper	IF	Citations
825	Dynamic Equivalent Circuit Model to Estimate State-Of-Health Of Lithium-Ion Batteries. <i>IEEE Access</i> , <b>2022</b> , 1-1	3.5	1
824	Learnable Wavelet Scattering Networks: Applications to Fault Diagnosis of Analog Circuits and Rotating Machinery. <i>Electronics (Switzerland)</i> , <b>2022</b> , 11, 451	2.6	0
823	Imbalanced bearing fault diagnosis under variant working conditions using cost-sensitive deep domain adaptation network. <i>Expert Systems With Applications</i> , <b>2022</b> , 193, 116459	7.8	5
822	Comparison between Synthetic Oil Lubricants for Reducing Fretting Degradation in Lightly Loaded Gold-Plated Contacts. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , <b>2022</b> , 1-1	1.7	
821	A machine learning-based framework for online prediction of battery ageing trajectory and lifetime using histogram data. <i>Journal of Power Sources</i> , <b>2022</b> , 526, 231110	8.9	2
820	The Distribution and Detection Issues of Counterfeit Lithium-Ion Batteries. <i>Energies</i> , <b>2022</b> , 15, 3798	3.1	2
819	A Review of Second-Life Lithium-Ion Batteries for Stationary Energy Storage Applications. <i>Proceedings of the IEEE</i> , <b>2022</b> , 110, 735-753	14.3	3
818	Life-cycle parameter identification method of an electrochemical model for lithium-ion battery pack. <i>Journal of Energy Storage</i> , <b>2021</b> , 47, 103591	7.8	5
817	Weighted Entropy Minimization Based Deep Conditional Adversarial Diagnosis Approach Under Variable Working Conditions. <i>IEEE/ASME Transactions on Mechatronics</i> , <b>2021</b> , 26, 2440-2450	5.5	6
816	. <i>IEEE Access</i> , <b>2021</b> , 9, 144726-144739	3.5	2
815	Copper Trace Fatigue Life Modeling for Rigid Electronic Assemblies. <i>IEEE Transactions on Device and Materials Reliability</i> , <b>2021</b> , 21, 79-86	1.6	4
814	Reliability modeling for multistage systems subject to competing failure processes. <i>Quality and Reliability Engineering International</i> , <b>2021</b> , 37, 2936-2949	2.6	0
813	Machine learning pipeline for battery state-of-health estimation. <i>Nature Machine Intelligence</i> , <b>2021</b> , 3, 447-456	22.5	45
812	Visual inspection of steel surface defects based on domain adaptation and adaptive convolutional neural network. <i>Mechanical Systems and Signal Processing</i> , <b>2021</b> , 153, 107541	7.8	11
811	Capacity-Fading Behavior Analysis for Early Detection of Unhealthy Li-Ion Batteries. <i>IEEE Transactions on Industrial Electronics</i> , <b>2021</b> , 68, 2659-2666	8.9	14
810	Deep Residual Networks With Adaptively Parametric Rectifier Linear Units for Fault Diagnosis. <i>IEEE Transactions on Industrial Electronics</i> , <b>2021</b> , 68, 2587-2597	8.9	44
809	Role of the rest period in capacity fade of Graphite/LiCoO <sub>2</sub> batteries. <i>Journal of Power Sources</i> , <b>2021</b> , 484, 229246	8.9	4

808	Hybrid electrochemical energy storage systems: An overview for smart grid and electrified vehicle applications. <i>Renewable and Sustainable Energy Reviews</i> , <b>2021</b> , 139, 110581	16.2	36
807	Charging induced electrode layer fracturing of 18650 lithium-ion batteries. <i>Journal of Power Sources</i> , <b>2021</b> , 484, 229260	8.9	4
806	Detection of intermittent faults based on an optimally weighted moving average T2 control chart with stationary observations. <i>Automatica</i> , <b>2021</b> , 123, 109298	5.7	14
805	Advanced battery management strategies for a sustainable energy future: Multilayer design concepts and research trends. <i>Renewable and Sustainable Energy Reviews</i> , <b>2021</b> , 138, 110480	16.2	57
804	Sparse Reconstruction for Microdefect Detection of Two-Dimensional Ultrasound Image Based on Blind Estimation. <i>IEEE Transactions on Industrial Electronics</i> , <b>2021</b> , 68, 10154-10161	8.9	1
803	A Deep Forest-Based Fault Diagnosis Scheme for Electronics-Rich Analog Circuit Systems. <i>IEEE Transactions on Industrial Electronics</i> , <b>2021</b> , 68, 10087-10096	8.9	8
802	Generalized sparse filtering for rotating machinery fault diagnosis. <i>Journal of Supercomputing</i> , <b>2021</b> , 77, 3402-3421	2.5	3
801	. <i>IEEE Access</i> , <b>2021</b> , 9, 89527-89532	3.5	2
800	A Machine Learning Degradation Model for Electrochemical Capacitors Operated at High Temperature. <i>IEEE Access</i> , <b>2021</b> , 9, 25544-25553	3.5	4
799	Nonparametric Model-Based Online Junction Temperature and State-of-Health Estimation for Insulated Gate Bipolar Transistors. <i>IEEE Access</i> , <b>2021</b> , 9, 95304-95316	3.5	0
798	Protection Devices in Commercial 18650 Lithium-Ion Batteries. <i>IEEE Access</i> , <b>2021</b> , 9, 66687-66695	3.5	5
797	Battery Stress Factor Ranking for Accelerated Degradation Test Planning Using Machine Learning. <i>Energies</i> , <b>2021</b> , 14, 723	3.1	6
796	. <i>IEEE Access</i> , <b>2021</b> , 1-1	3.5	1
795	Lithium-iron-phosphate battery electrochemical modelling under a wide range of ambient temperatures. <i>Journal of Electroanalytical Chemistry</i> , <b>2021</b> , 882, 115041	4.1	4
794	Effects of external pressure on phase stability and diffusion rate in lithium-ion cells. <i>Journal of Electroanalytical Chemistry</i> , <b>2021</b> , 895, 115400	4.1	0
793	A mathematical method for open-circuit potential curve acquisition for lithium-ion batteries. <i>Journal of Electroanalytical Chemistry</i> , <b>2021</b> , 895, 115488	4.1	1
792	Hybrid remaining useful life prediction method. A case study on railway D-cables. <i>Reliability Engineering and System Safety</i> , <b>2021</b> , 213, 107746	6.3	7
791	Development of an Informative Lithium-Ion Battery Datasheet. <i>Energies</i> , <b>2021</b> , 14, 5434	3.1	2

790	The significance of aqueous binders in lithium-ion batteries. <i>Renewable and Sustainable Energy Reviews</i> , <b>2021</b> , 147, 111227	16.2	11
789	Mitigation strategies for Li-ion battery thermal runaway: A review. <i>Renewable and Sustainable Energy Reviews</i> , <b>2021</b> , 150, 111437	16.2	20
788	Decoupling the thermal and non-thermal effects of discharge C-rate on the capacity fade of lithium-ion batteries. <i>Journal of Power Sources</i> , <b>2021</b> , 510, 230390	8.9	1
787	Joint Estimation of Inconsistency and State of Health for Series Battery Packs. <i>Automotive Innovation</i> , <b>2021</b> , 4, 103-116	1.7	11
786	An Assessment of Validity of the Bathtub Model Hazard Rate Trends in Electronics. <i>IEEE Access</i> , <b>2021</b> , 9, 10282-10290	3.5	5
785	. <i>IEEE Access</i> , <b>2021</b> , 1-1	3.5	2
784	Development of a cycle counting algorithm with temporal parameters. <i>Microelectronics Reliability</i> , <b>2020</b> , 109, 113652	1.2	
783	Sparse auto-encoder with regularization method for health indicator construction and remaining useful life prediction of rolling bearing. <i>Measurement Science and Technology</i> , <b>2020</b> , 31, 105005	2	10
782	. <i>IEEE Access</i> , <b>2020</b> , 8, 101859-101866	3.5	5
781	Artificial Intelligence Trends Based on the Patents Granted by the United States Patent and Trademark Office. <i>IEEE Access</i> , <b>2020</b> , 8, 81633-81643	3.5	9
780	Aging modes analysis and physical parameter identification based on a simplified electrochemical model for lithium-ion batteries. <i>Journal of Energy Storage</i> , <b>2020</b> , 31, 101538	7.8	17
779	Data-driven reliability analysis of Boeing 787 Dreamliner. <i>Chinese Journal of Aeronautics</i> , <b>2020</b> , 33, 1969-1979	10	
778	An analytical model for the CC-CV charge of Li-ion batteries with application to degradation analysis. <i>Journal of Energy Storage</i> , <b>2020</b> , 29, 101342	7.8	8
777	Degradation Monitoring of Insulation Systems Used in Low-Voltage Electromagnetic Coils under Thermal Loading Conditions from a Creep Point of View. <i>Sensors</i> , <b>2020</b> , 20,	3.8	1
776	. <i>IEEE Access</i> , <b>2020</b> , 8, 21326-21332	3.5	3
775	Two-level fault diagnosis RBF networks for auto-transformer rectifier units using multi-source features. <i>Journal of Power Electronics</i> , <b>2020</b> , 20, 754-763	0.9	6
774	Improved electromagnetic coil insulation health monitoring using equivalent circuit model analysis. <i>International Journal of Electrical Power and Energy Systems</i> , <b>2020</b> , 119, 105829	5.1	5
773	Online Degradation State Assessment Methodology for Multi-Mode Failures of Insulated Gate Bipolar Transistor. <i>IEEE Access</i> , <b>2020</b> , 8, 69471-69481	3.5	2

772	An improved empirical wavelet transform method for rolling bearing fault diagnosis. <i>Science China Technological Sciences</i> , <b>2020</b> , 63, 2231-2240	3.5	8
771	Detection and Isolation of Wheelset Intermittent Over-Creeps for Electric Multiple Units Based on a Weighted Moving Average Technique. <i>IEEE Transactions on Intelligent Transportation Systems</i> , <b>2020</b> , 1-14	6.1	3
770	Connector Housing <b>2020</b> , 17-30		
769	Signal Connector Selection <b>2020</b> , 251-260		0
768	Advanced Technology Attachment Connectors <b>2020</b> , 261-274		
767	Fretting in Connectors <b>2020</b> , 147-172		
766	Examples of Connectors <b>2020</b> , 313-329		
765	Power Connectors <b>2020</b> , 275-288		
764	What Is an Electrical Connector? <b>2020</b> , 1-15		
763	Contact Plating <b>2020</b> , 43-65		
762	Contact Interface <b>2020</b> , 75-88		
761	The Back-End Connection <b>2020</b> , 89-101		
760	Appendix A Standards <b>2020</b> , 331-345		
759	Contact Spring <b>2020</b> , 31-42		
758	Selecting the Right Connector <b>2020</b> , 207-249		
757	Supplier Selection <b>2020</b> , 197-205		
756	Loads and Failure Mechanisms <b>2020</b> , 103-145		
755	Insertion and Extraction Forces <b>2020</b> , 67-74		

754	Computed Tomography Analysis of Li-Ion Battery Case Ruptures. <i>Fire Technology</i> , <b>2020</b> , 56, 2565-2578	3	7
753	Battery Lifetime Prognostics. <i>Joule</i> , <b>2020</b> , 4, 310-346	27.8	200
752	A Local Adaptive Minority Selection and Oversampling Method for Class-Imbalanced Fault Diagnostics in Industrial Systems. <i>IEEE Transactions on Reliability</i> , <b>2020</b> , 69, 1195-1206	4.6	8
751	Multiple wavelet regularized deep residual networks for fault diagnosis. <i>Measurement: Journal of the International Measurement Confederation</i> , <b>2020</b> , 152, 107331	4.6	19
750	Battery warm-up methodologies at subzero temperatures for automotive applications: Recent advances and perspectives. <i>Progress in Energy and Combustion Science</i> , <b>2020</b> , 77, 100806	33.6	98
749	Experimental Approach to Determine Damage Curves for SnAgCu Solder Under Sequential Cyclic Loads. <i>Journal of Electronic Materials</i> , <b>2020</b> , 49, 1412-1420	1.9	1
748	Remaining useful life estimation of lithium-ion cells based on k-nearest neighbor regression with differential evolution optimization. <i>Journal of Cleaner Production</i> , <b>2020</b> , 249, 119409	10.3	27
747	Detection and detectability of intermittent faults based on moving average T2 control charts with multiple window lengths. <i>Journal of Process Control</i> , <b>2020</b> , 92, 296-309	3.9	2
746	Multi-Objective Optimization Design of a Notch Filter Based on Improved NSGA-II for Conducted Emissions. <i>IEEE Access</i> , <b>2020</b> , 8, 83213-83223	3.5	9
745	Reliability analysis of multilayer polymer aluminum electrolytic capacitors. <i>Microelectronics Reliability</i> , <b>2020</b> , 112, 113725	1.2	6
744	Experimental verification of lithium-ion battery prognostics based on an interacting multiple model particle filter. <i>Transactions of the Institute of Measurement and Control</i> , <b>2020</b> , 014233122096157	1.8	1
743	Early detection of anomalous degradation behavior in lithium-ion batteries. <i>Journal of Energy Storage</i> , <b>2020</b> , 32, 101710	7.8	7
742	Board-Level Lifetime Prediction for Power Board of Balise Transmission Module in High-Speed Railways. <i>IEEE Access</i> , <b>2020</b> , 8, 135011-135024	3.5	3
741	Assembly Options and Challenges for Electronic Products With Lead-Free Exemption. <i>IEEE Access</i> , <b>2020</b> , 8, 134194-134208	3.5	2
740	Artificial Intelligence-Related Research Funding by the U.S. National Science Foundation and the National Natural Science Foundation of China. <i>IEEE Access</i> , <b>2020</b> , 8, 183448-183459	3.5	3
739	Translation Invariance-Based Deep Learning for Rotating Machinery Diagnosis. <i>Shock and Vibration</i> , <b>2020</b> , 2020, 1-16	1.1	2
738	Electrical Connectors for Underwater Applications <b>2020</b> , 289-311		
737	Electrostatic Charging of a Human Body Caused by Activities and Material Combinations in Hospitals. <i>IEEE Transactions on Electromagnetic Compatibility</i> , <b>2020</b> , 62, 315-323	2	1

736	Fault Diagnosis Using Adaptive Multifractal Detrended Fluctuation Analysis. <i>IEEE Transactions on Industrial Electronics</i> , <b>2020</b> , 67, 2272-2282	8.9	21
735	Deep Residual Shrinkage Networks for Fault Diagnosis. <i>IEEE Transactions on Industrial Informatics</i> , <b>2020</b> , 16, 4681-4690	11.9	181
734	Reliability design and case study of the domestic compressor subjected to repetitive internal stresses. <i>Reliability Engineering and System Safety</i> , <b>2020</b> , 193, 106604	6.3	11
733	Parameter updating method of a simplified first principles-thermal coupling model for lithium-ion batteries. <i>Applied Energy</i> , <b>2019</b> , 256, 113924	10.7	6
732	Effect of different lubricant films on contact resistance of stationary separable gold-plated electrical contacts. <i>Journal of Materials Science: Materials in Electronics</i> , <b>2019</b> , 30, 14368-14381	2.1	1
731	A Comparative Study of Deep Learning-Based Diagnostics for Automotive Safety Components Using a Raspberry Pi <b>2019</b> ,		1
730	State of charge-dependent aging mechanisms in graphite/Li(NiCoAl)O <sub>2</sub> cells: Capacity loss modeling and remaining useful life prediction. <i>Applied Energy</i> , <b>2019</b> , 255, 113818	10.7	17
729	Methods for fault diagnosis of high-speed railways: A review. <i>Proceedings of the Institution of Mechanical Engineers, Part O: Journal of Risk and Reliability</i> , <b>2019</b> , 233, 908-922	0.8	9
728	A Rotating Machinery Fault Diagnosis Method Based on Feature Learning of Thermal Images. <i>IEEE Access</i> , <b>2019</b> , 7, 12348-12359	3.5	41
727	Simulation and Experimental Verification of Edge Blurring Phenomenon in Microdefect Inspection Based on High-Frequency Ultrasound. <i>IEEE Access</i> , <b>2019</b> , 7, 11515-11525	3.5	11
726	Fault detection isolation and diagnosis of multi-axle speed sensors for high-speed trains. <i>Mechanical Systems and Signal Processing</i> , <b>2019</b> , 131, 183-198	7.8	15
725	Predicting Damage and Life Expectancy of Subsea Power Cables in Offshore Renewable Energy Applications. <i>IEEE Access</i> , <b>2019</b> , 7, 54658-54669	3.5	18
724	The Explosive Nature of Tab Burrs in Li-Ion Batteries. <i>IEEE Access</i> , <b>2019</b> , 7, 45978-45982	3.5	5
723	Breaking the Trust: How Companies Are Failing Their Customers. <i>IEEE Access</i> , <b>2019</b> , 7, 52522-52531	3.5	
722	Effect of metal foams on the dynamic response time of a magnetorheological damper. <i>International Journal of Applied Electromagnetics and Mechanics</i> , <b>2019</b> , 61, 185-199	0.4	1
721	Water-Resistant Smartphone Technologies. <i>IEEE Access</i> , <b>2019</b> , 7, 42757-42773	3.5	6
720	. <i>IEEE Transactions on Device and Materials Reliability</i> , <b>2019</b> , 19, 176-188	1.6	3
719	. <i>IEEE Access</i> , <b>2019</b> , 7, 24082-24095	3.5	14

718	Maximizing Network Resilience against Malicious Attacks. <i>Scientific Reports</i> , <b>2019</b> , 9, 2261	4.9	6
717	Lithium-Ion Battery Health Prognosis Based on a Real Battery Management System Used in Electric Vehicles. <i>IEEE Transactions on Vehicular Technology</i> , <b>2019</b> , 68, 4110-4121	6.8	141
716	System-Level Fault Prognosis for High-Speed Railway On-Board Systems. <i>Transportation Research Record</i> , <b>2019</b> , 2673, 584-595	1.7	2
715	Ultrasonic Health Monitoring of Lithium-Ion Batteries. <i>Electronics (Switzerland)</i> , <b>2019</b> , 8, 751	2.6	20
714	A Domain Adaptive Convolutional LSTM Model for Prognostic Remaining Useful Life Estimation Under Variant Conditions <b>2019</b> ,		7
713	Aging characteristics-based health diagnosis and remaining useful life prognostics for lithium-ion batteries. <i>ETransportation</i> , <b>2019</b> , 1, 100004	12.7	48
712	Life cycle trends of electronic materials, processes and components. <i>Microelectronics Reliability</i> , <b>2019</b> , 99, 262-276	1.2	7
711	State of charge estimation based on a thermal coupling simplified first-principles model for lithium-ion batteries. <i>Journal of Energy Storage</i> , <b>2019</b> , 25, 100838	7.8	10
710	Algorithm to Determine the Knee Point on Capacity Fade Curves of Lithium-Ion Cells. <i>Energies</i> , <b>2019</b> , 12, 2910	3.1	19
709	. <i>IEEE Access</i> , <b>2019</b> , 7, 71131-71141	3.5	8
708	Accelerated cycle life testing and capacity degradation modeling of LiCoO <sub>2</sub> -graphite cells. <i>Journal of Power Sources</i> , <b>2019</b> , 435, 226830	8.9	41
707	Transmission characteristics analysis of an MCR-WPT system with SP resonance structure based on harmonic current influence. <i>IEICE Electronics Express</i> , <b>2019</b> , 16, 20190460-20190460	0.5	
706	A Weighted Deep Domain Adaptation Method for Industrial Fault Prognostics According to Prior Distribution of Complex Working Conditions. <i>IEEE Access</i> , <b>2019</b> , 7, 139802-139814	3.5	16
705	Perceptual Vibration Hashing by Sub-Band Coding: An Edge Computing Method for Condition Monitoring. <i>IEEE Access</i> , <b>2019</b> , 7, 129644-129658	3.5	2
704	ACA Curing Process Optimization Based on Curing Degree Considering Shear Strength of Joints. <i>IEEE Access</i> , <b>2019</b> , 7, 182906-182915	3.5	
703	Electronic Circuit Diagnosis with No Data <b>2019</b> ,		2
702	The Use of UL 1642 Impact Testing for Li-ion Pouch Cells. <i>IEEE Access</i> , <b>2019</b> , 7, 176706-176711	3.5	1
701	Multiple Wavelet Coefficients Fusion in Deep Residual Networks for Fault Diagnosis. <i>IEEE Transactions on Industrial Electronics</i> , <b>2019</b> , 66, 4696-4706	8.9	84



700	Metallized film capacitors used for EMI filtering: A reliability review. <i>Microelectronics Reliability</i> , <b>2019</b> , 92, 123-135	1.2	17
699	Accelerated degradation model for C-rate loading of lithium-ion batteries. <i>International Journal of Electrical Power and Energy Systems</i> , <b>2019</b> , 107, 438-445	5.1	43
698	Reduction of Li-ion Battery Qualification Time Based on Prognostics and Health Management. <i>IEEE Transactions on Industrial Electronics</i> , <b>2019</b> , 66, 7310-7315	8.9	17
697	Plastic encapsulant materials <b>2019</b> , 47-121		2
696	Qualification and quality assurance <b>2019</b> , 375-429		
695	Validation and verification of a hybrid method for remaining useful life prediction of lithium-ion batteries. <i>Journal of Cleaner Production</i> , <b>2019</b> , 212, 240-249	10.3	53
694	Lithium-Ion Battery Remaining Useful Life Prediction With Box-Cox Transformation and Monte Carlo Simulation. <i>IEEE Transactions on Industrial Electronics</i> , <b>2019</b> , 66, 1585-1597	8.9	103
693	Phthalates in Electronics: The Risks and the Alternatives. <i>IEEE Access</i> , <b>2018</b> , 6, 6232-6242	3.5	14
692	Malfunctions of Medical Devices Due to Electrostatic Occurrences Big Data Analysis of 10 Years of the FDA Reports. <i>IEEE Access</i> , <b>2018</b> , 6, 5805-5811	3.5	17
691	Managing Electronics Part Changes in the Supply Chain. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , <b>2018</b> , 8, 883-895	1.7	0
690	Life Prediction. <i>Springer Series in Reliability Engineering</i> , <b>2018</b> , 115-139	0.2	
689	. <i>IEEE Access</i> , <b>2018</b> , 6, 18088-18107	3.5	30
688	Detection of Generalized-Roughness and Single-Point Bearing Faults Using Linear Prediction-Based Current Noise Cancellation. <i>IEEE Transactions on Industrial Electronics</i> , <b>2018</b> , 65, 9728-9738	8.9	22
687	Long Short-Term Memory Recurrent Neural Network for Remaining Useful Life Prediction of Lithium-Ion Batteries. <i>IEEE Transactions on Vehicular Technology</i> , <b>2018</b> , 67, 5695-5705	6.8	366
686	Evaluating Characteristics of Electrostatic Discharge (ESD) Events in Wearable Medical Devices: Comparison With the IEC 61000-4-2 Standard. <i>IEEE Transactions on Electromagnetic Compatibility</i> , <b>2018</b> , 60, 1304-1312	2	10
685	Deep Residual Networks With Dynamically Weighted Wavelet Coefficients for Fault Diagnosis of Planetary Gearboxes. <i>IEEE Transactions on Industrial Electronics</i> , <b>2018</b> , 65, 4290-4300	8.9	180
684	Risk of tin whiskers in the nuclear industry. <i>Microelectronics Reliability</i> , <b>2018</b> , 81, 22-30	1.2	3
683	The effect of epoxy/glass interfaces on CAF failures in printed circuit boards. <i>Microelectronics Reliability</i> , <b>2018</b> , 82, 235-243	1.2	6

682	How Poor Reliability Affects Warranties: An Analysis of General Motors Powertrain Warranty Reduction. <i>IEEE Access</i> , <b>2018</b> , 6, 15065-15074	3.5	3
681	An adaptive state of charge estimation approach for lithium-ion series-connected battery system. <i>Journal of Power Sources</i> , <b>2018</b> , 392, 48-59	8.9	29
680	A review of fractional-order techniques applied to lithium-ion batteries, lead-acid batteries, and supercapacitors. <i>Journal of Power Sources</i> , <b>2018</b> , 390, 286-296	8.9	233
679	Prognostics and Health Management. <i>Springer Series in Reliability Engineering</i> , <b>2018</b> , 447-507	0.2	1
678	Exploding E-Cigarettes: A Battery Safety Issue. <i>IEEE Access</i> , <b>2018</b> , 6, 21442-21466	3.5	26
677	In-Situ Observations of Lithium Dendrite Growth. <i>IEEE Access</i> , <b>2018</b> , 6, 8387-8393	3.5	22
676	. <i>IEEE Systems Journal</i> , <b>2018</b> , 12, 2509-2523	4.3	27
675	Electronic Circuit Health Estimation Through Kernel Learning. <i>IEEE Transactions on Industrial Electronics</i> , <b>2018</b> , 65, 1585-1594	8.9	12
674	Fault Diagnostics and Lifetime Prognostics for Phosphor-Converted White LED Packages. <i>Solid State Lighting Technology and Application Series</i> , <b>2018</b> , 255-299	0.7	2
673	Autonomous health management for PMSM rail vehicles through demagnetization monitoring and prognosis control. <i>ISA Transactions</i> , <b>2018</b> , 72, 245-255	5.5	13
672	Joint PHY/MAC Layer Security Design Using ARQ With MRC and Null-Space Independent PAPR-Aware Artificial Noise in SISO Systems. <i>IEEE Transactions on Wireless Communications</i> , <b>2018</b> , 17, 6190-6204	9.6	19
671	A Unique Failure Mechanism in the Nexus 6P Lithium-Ion Battery. <i>Energies</i> , <b>2018</b> , 11, 841	3.1	4
670	Physics-of-Failure Approach for Electronics. <i>Springer Series in Reliability Engineering</i> , <b>2018</b> , 417-445	0.2	
669	Introduction to PHM <b>2018</b> , 1-37		2
668	PHM of Li-ion Batteries <b>2018</b> , 349-375		2
667	PHM in Healthcare <b>2018</b> , 431-449		
666	Analysis of PHM Patents for Electronics <b>2018</b> , 613-647		
665	Physics-of-Failure Approach to PHM <b>2018</b> , 61-84		

664	Machine Learning: Data Pre-processing <b>2018</b> , 111-130		3
663	Sensor Systems for PHM <b>2018</b> , 39-60		
662	A critique of reliability prediction techniques for avionics applications. <i>Chinese Journal of Aeronautics</i> , <b>2018</b> , 31, 10-20	3.7	16
661	. <i>IEEE Transactions on Industrial Electronics</i> , <b>2018</b> , 65, 1526-1538	8.9	142
660	Performance Degradation of Hydraulic Vehicle Dampers <b>2018</b> ,		2
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450	A canary device based approach for prognosis of Ball Grid Array packages <b>2012</b> ,		4
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356	Symbolic time series analysis based health condition forecasting in complex electronic systems <b>2010,</b>		1
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299	Encapsulation Defects and Failures <b>2009</b> , 225-285		
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